

注記
NOTES:

1.材質
MATERIAL
ハウジング:液晶ポリマー(LCP)、ナチュラル(白)、ガラス充填、UL94V-0
HOUSING: LIQUID CRYSTAL POLYMER(LCP), NATURAL (WHITE)
GLASS FILLED, UL94V-0
アクチュエータ: ポリフェニレンサルファイド(PPS)、黒色、ガラス充填、UL94V-0
ACTUATOR: POLYPHENYLENE SULFIDE(PPS), BLACK
GLASS FILLED, UL94V-0
ターミナル: 銅合金 (t=0.12)
TERMINAL: COPPER ALLOY (t=0.12)
金具: リン青銅 (t=0.12)
NAIL: PHOS-BRO (t=0.12)

2.めっき仕様
PLATING
ターミナル
TERMINAL
接点部: 金めっき 0.1μm以上
CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM.
半田付け部: 金めっき
SOLDER TAIL AREA: GOLD
下地めっき: ニッケル 1.0μm以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM.
金具
NAIL
錫めっき 1.0μm以上
TIN PLATING 1.0 MICROMETER MINIMUM.
下地めっき: ニッケル 1.0μm以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM.

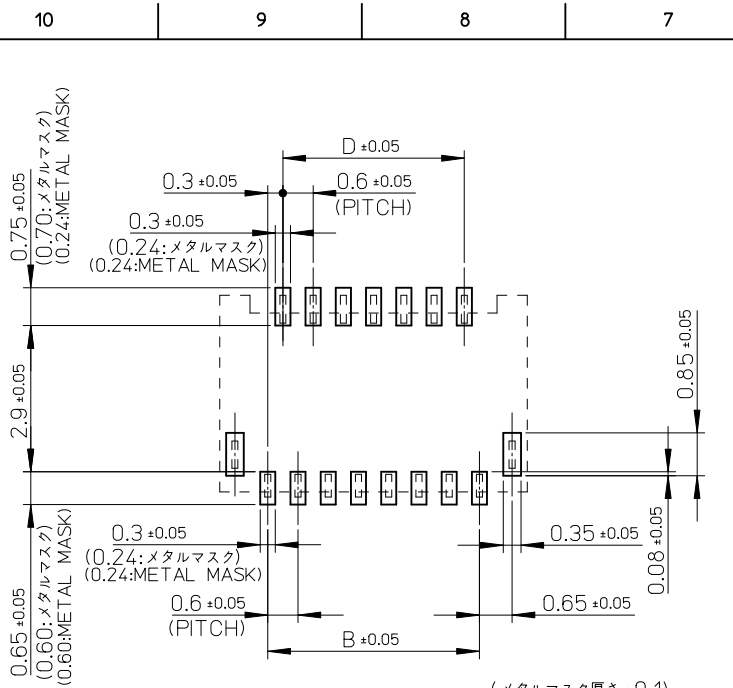
3.平坦度は、0.1ミリ以下とする。
TAILS COPLANARITY TO BE 0.1 MAXIMUM.

4.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

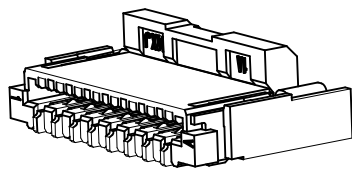
0.208	21.6	23.5	22.2	24.1	503425-7591	75
0.171	17.4	19.3	18.0	19.9	503425-6191	61
重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES No. 503425-xx11

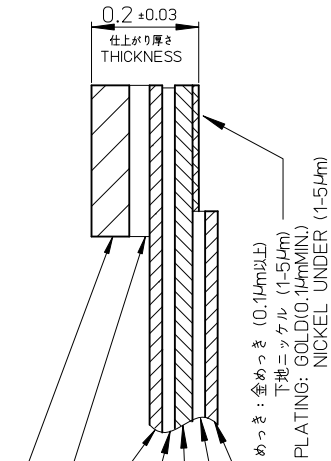
RELEASED EC NO.: J2010-2422 DRW: KUSATO 2009/04/28 CH: D: HSHIMOYAMA 2010/05/28 APPR: KMORIKAWA 2010/05/31	DESCRIPTION REV: O	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY	DATE	TITLE						
		10 OVER 30 UNDER	±0.25	KUSATO	2008/11/14	0.3 FPC CONN. BACK FLIP HOUSING ASSY						
		30 OVER	±0.3	CHECKED BY	DATE	MOLEX INCORPORATED						
		ANGULAR	±1 °	HSHIMOYAMA	2008/11/14	DOCUMENT NO. SD-503425-001						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY		DATE		MATERIAL NO.		SHEET NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
		HHIRATA		2008/11/14		SEE TABLE		1 OF 2				



推奨基板寸法
RECOMMENDED P.W.B. PATTERN LAYOUT
(メタルマスク厚さ: 0.1)
(METAL MASK THICKNESS: 0.1)

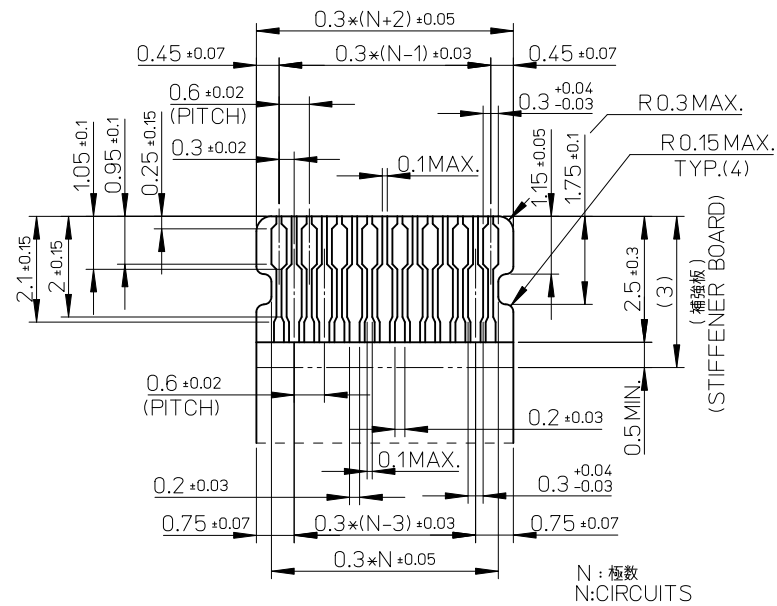


ISO VIEW (参考)



- 補強板: ポリイミド REINFORCE BOARD: POLYIMIDE
- 熱硬化接着剤 THERMOSETTING ADHESIVE
- ベースフィルム: ポリイミド (25µm) BASE FILM: POLYIMIDE (25µm)
- 熱硬化接着剤 THERMOSETTING ADHESIVE
- 導体部: 銅箔 (35µm) CONDUCTOR: COPPER FOIL (35µm)
- 熱硬化接着剤 THERMOSETTING ADHESIVE
- カバーレイ: ポリイミド (25µm) COVER FILM: POLYIMIDE (25µm)

FPC構成推奨仕様
STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

FPCについて:

- 抜き方向は、導体側から補強板側を推奨致します。
- 補強フィルム材質は、ポリイミドを推奨致します。
- 接着剤は熱硬化接着剤を推奨致します。
- 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

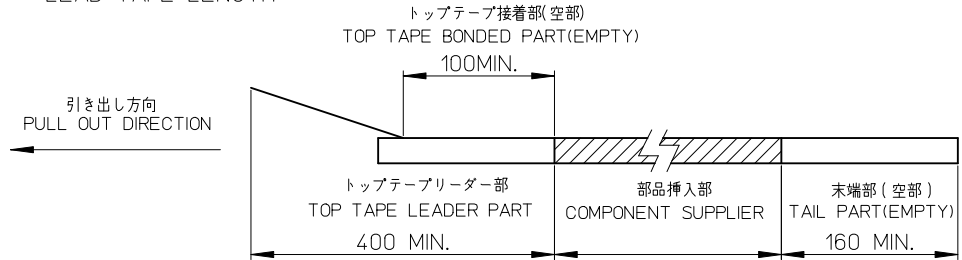
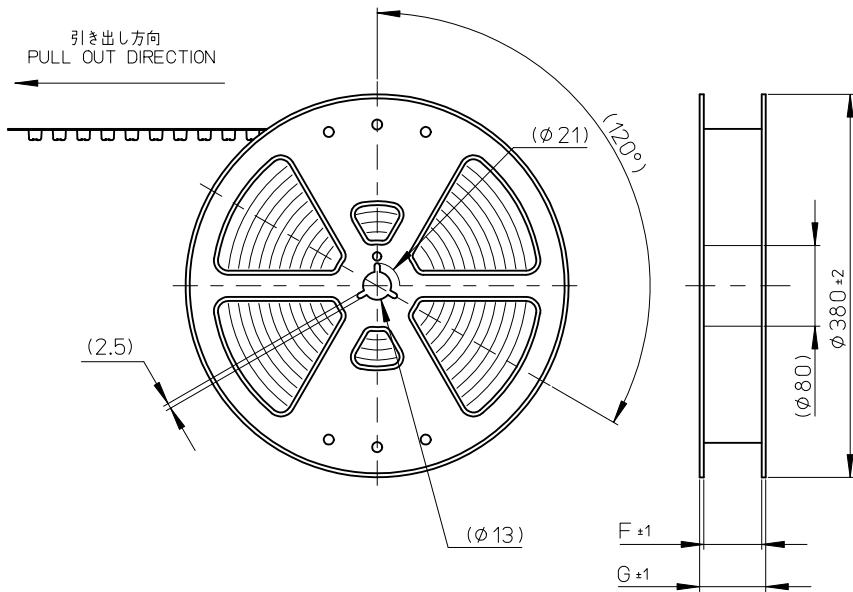
ABOUT FPC:

- RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
- RECOMMENDED MATERIAL:
STIFFENER FILM: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
- PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE
CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

SEE SHEET 1 EC NO: J2010-2422 DRWN: KUSATO 2009/04/28 CHKD: HSHIMOYAMA 2010/05/28 APPR: KMORIKAWA 2010/05/31	DESCRIPTION REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY	DATE	TITLE	0.3 FPC CONN. BACK FLIP HOUSING ASSY		
		10 OVER 30 UNDER	± 0.25	KUSATO	2008/11/14	MOLEX INCORPORATED			
		30 OVER	± 0.3	CHECKED BY	DATE				SD-503425-001
ANGULAR ± 1 °		APPROVED BY	DATE	DOCUMENT NO.		SHEET NO.		2 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		HHRATA	2008/11/14	SEE TABLE		SD-503425-001			
				SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
				A3					

注記)
NOTES

- 製品番号503425-**11の詳細寸法は、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 503425-**11 DETAIL DIMENSIONS,
SEE SALES DRAWING FOR CONNECTOR.
- 梱包数量: 3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH

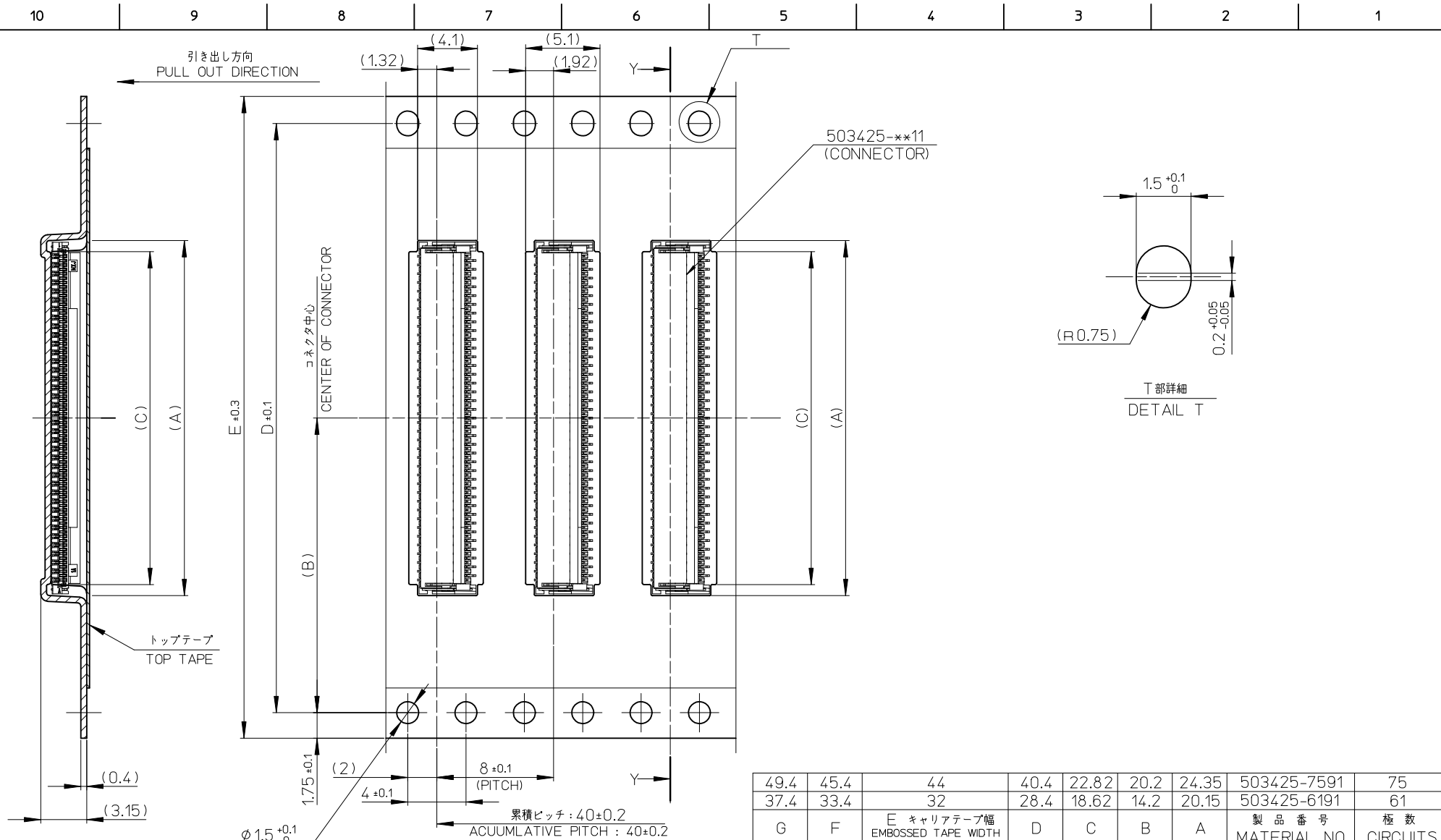


- カバーテープの剥離強度については、IEC60286-3に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.

5. 材料

MATERIAL
 キャリアテープ: ポリスチレン (PS)
 CARRIER TAPE: POLYSTYRENE (PS)
 トップテープ: PET, PE, PEF
 TOP TAPE : PET, PE, PEF
 リール: ポリスチレン
 REEL: POLYSTYLENE
 6. ELV及びRoHS適合品
 ELV AND LoHS COMPLIANT

RELEASED EC NO.: J2010-2422 DRWN: KUSATO 2008/11/19 CH'KD: HSHIMOYAMA 2010/05/28 APPR: KMORIKAWA 2010/05/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY KUSATO	DATE 2008/11/19	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (503425-**11 SERIES)			
	10 OVER 30 UNDER	± ---	CHECKED BY HSHIMOYAMA	DATE 2008/11/19				
	30 OVER	± ---	APPROVED BY HHIRATA	DATE 2008/11/19	MOLEX INCORPORATED			
ANGULAR ±1 °		MATERIAL NO. SEE SHEET 1 OF 2		DOCUMENT NO. SD-503425-002				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



49.4	45.4	44	40.4	22.82	20.2	24.35	503425-7591	75	
37.4	33.4	32	28.4	18.62	14.2	20.15	503425-6191	61	
G	F	E キャリアテープ幅 EMBOSSED TAPE WIDTH		D	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

SEE SHEET 1 OF 2 EC NO: J2010-2422 DRWN: KUSATO 2008/11/27 CH'KD: HSHIMUYAMA 2010/05/28 APPR: KMORI KAWA 2010/05/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY KUSATO	DATE 2008/11/19	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (503425-**11 SERIES)			
	10 OVER 30 UNDER	± ---	CHECKED BY HSHIMUYAMA	DATE 2008/11/19	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY HHIRATA	DATE 2008/11/19				
ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-503425-002		2 OF 2		
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						